

IN THE SPECIFICATION

Please replace the following paragraph beginning on page 1, line 10 with the following:

In recent years, accompanying the miniaturization of wiring in semiconductor integrated circuits, signal delay problems can occur. To solve these problems, there has signal delay has arisen problems accompanying the miniaturization of wiring in semiconductor integrated circuits. In order to solve the problems of the signal delay, there have been proposed a method for lowering the wiring resistance using copper as wiring material, and a method for lowering capacitance using a low-dielectric-constant film (low-k dielectric film) as an interlayer insulating film.